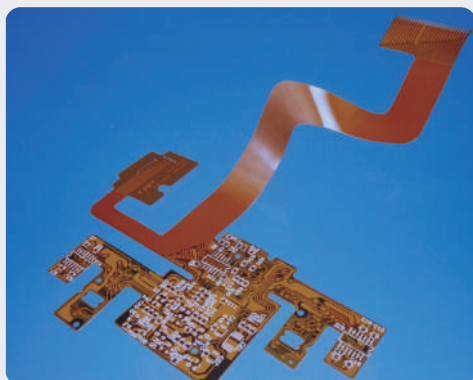


Copper EMI Shielding and Jumper Paste

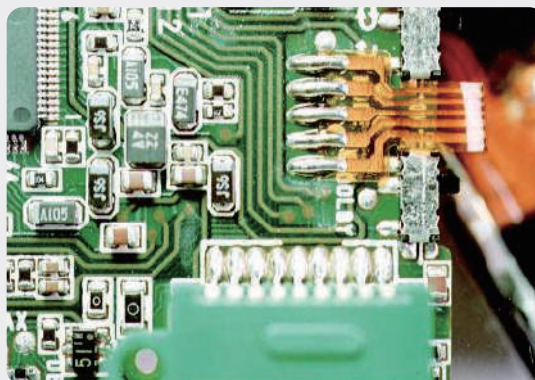
Over 20-year experience, cost-performance copper paste

Applications

EMI shielding



Jumper



Features

- Low cost copper particles
- Low cost EMI solution
- Lower resistance



Product line-up & properties

Product			NF2000EX
Filler	Conductive particles		Copper
Binder	Resin		Phenolic
Solvent			Butyl carbitol acetate (Diethylene glycol monobutyl ether)
Viscosity	BH type	dPa·s	75 - 85
Density		g/cm ³	3.0 - 3.4
Curing (drying) conditions	Curing		160°C × 60min.
Volume resistivity(Representative value)		Ω·cm	5.0E-05
Sheet resistivity			25mΩ/□
Glass-transition temperature/Tg		°C	100
Shelf-life	0 - 5 °C	month(s)	3.0

